SDLS043 - DECEMBER 1983 - REVISED MARCH 1988

- D-C Triggered from Active-High or Active-Low Gated Logic Inputs
- Retriggerable for Very Long Output Pulses, Up to 100% Duty Cycle
- Overriding Clear Terminates Output Pulse
- '122 and 'LS122 Have Internal Timing Resistors

description

These d-c triggered multivibrators feature output pulse-duration control by three methods. The basic pulse time is programmed by selection of external resistance and capacitance values (see typical application data). The '122 and 'LS122 have internal timing resistors that allow the circuits to be used with only an external capacitor, if so desired. Once triggered, the basic pulse duration may be extended by retriggering the gated low-level-active (A) or high-level-active (B) inputs, or be reduced by use of the overriding clear. Figure 1 illustrates pulse control by retriggering and early clear.

The 'LS122 and 'LS123 are provided enough Schmitt hysteresis to ensure jitter-free triggering from the B input with transition rates as slow as 0.1 millivolt per nanosecond.

The $R_{\mbox{\scriptsize int}}$ in nominall 10 $k\Omega$ for '122 and 'LS122.

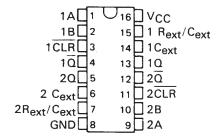
SN54122, SN54LS122...J OR W PACKAGE SN74122...N PACKAGE SN74LS122...D OR N PACKAGE (TOP VIEW) (SEE NOTES 1 THRU 4)

A1 🗆	1	U 14		Vcc
A2 🗀	2	13		R _{ext} /C _{ext}
B1 □	3	12	Þ	NC
B2 ☐	4	11		C _{ext}
CLR	5	10		NC
ō۲	6	9	þ	Rint
GND□	7	8		Q

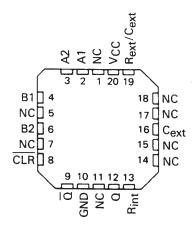
NOTES: 1. An external timing capacitor may be connected between C_{ext} and Re_{xt}/C_{ext} (positive).

- To use the internal timing resistor of '122 or 'LS122, connect R_{int} to V_{CC}.
- For improved pulse duration accuracy and repeatability, connect an external resistor between R_{ext}/Ce_{xt} and V_{CC} with R_{int} open-circuited.
- To obtain variable pulse durations, connect an external variable resistance between R_{int} or R_{ext}/C_{ext} and VCC.

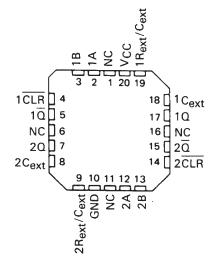
SN54123, SN54130, SN54LS123...J OR W PACKAGE SN74123, SN74130...N PACKAGE SN74LS123...D OR N PACKAGE (TOP VIEW) (SEE NOTES 1 THRU 4)



SN54LS122 . . . FK PACKAGE (TOP VIEW) (SEE NOTES 1 THRU 4)



SN54LS123 . . . FK PACKAGE (TOP VIEW) (SEE NOTES 1 THRU 4)



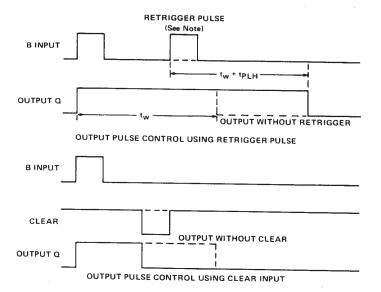
NC - No internal connection

PRODUCTION DATA information is current as of publication date. Products conform to specifications per the terms of Texas Instruments standard warranty. Production processing does not necessarily include testing of all parameters.



SDLS043 - DECEMBER 1983 - REVISED MARCH 1988

description (continued)



NOTE: Retrigger pulses starting before 0.22 C_{ext} (in picofrads) nanoseconds after the initial trigger pulse will be ignored and the output duration will remain unchanged.

FIGURE 1-TYPICAL INPUT/OUTPUT PULSES

'122, 'L\$122 **FUNCTION TABLE**

	INP	JTS			OUT	UTS
CLEAR	Α1	A2	В1	B2	Q	ā
L	Х	X	Х	Х	L	Н
×	н	Н	Х	×	L†	нŤ
×	Х	X	L	Х	L†	н†
×	Х	Х	Х	L	L†	нŤ
н	L	Х	1	Н	Λ	U
н	L	Χ	Н	1	Л	IJ
н	Х	L	↑	Н	7.	v
н	Х	L	Н	†	Л	U
н	Н	1	Н	Н	V	IJ
н	1	\downarrow	Н	н	V	J.
н	1	Н	Н	н	Л	u
1	L	X	Н	н	7	U
_ †	×	L	Н	н	7	v

'123, '130, 'LS123 **FUNCTION TABLE**

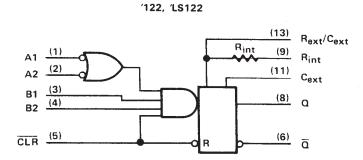
INPL	JTS		оит	OUTPUTS				
CLEAR	Α	В	α	ā				
L	Х	X	L	Н				
×	Н	X	L†	н†				
Х	х	L	L†	нŤ				
Н	L	†	Л	U				
Н	ţ	Н	Л	U				
1	L	Н	7	v				

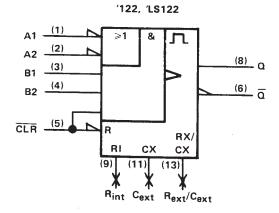
See explanation of function tables on page

† These lines of the functional tables assume that the indicated steady-state conditons at the A and B inputs have been set up long enough to complete any pulse started before the set up.

logic diagram (positive logic)

logic symbol†

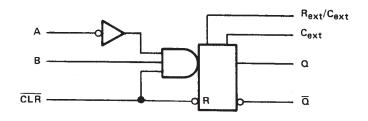




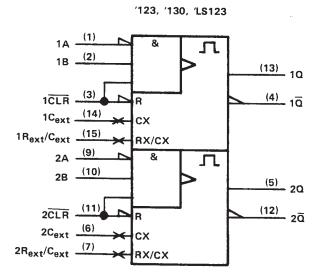
 $R_{\mbox{\scriptsize int}}$ is nominally 10 $k\Omega$ for '122 and 'LS122

logic diagram (positive logic) (each multivibrator)

'123, '130, 'L\$123



logic symbol†



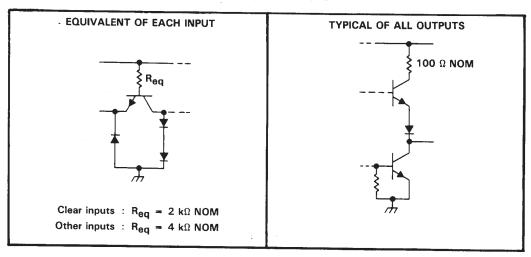
Pin numbers shown are for D, J, N, and W packages.

[†]These symbols are in accordance with ANSI/IEEE Std 91-1984 and IEC Publication 617-12.

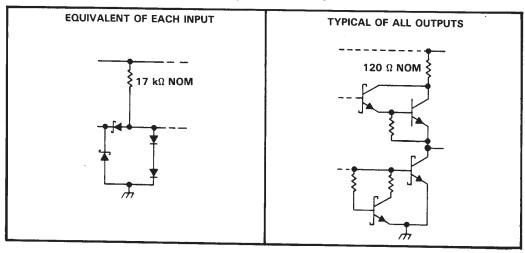
SDLS043 - DECEMBER 1983 - REVISED MARCH 1988

schematics of inputs and outputs

'122, '123, '130 CIRCUITS



'LS122, 'LS123 CIRCUITS



absolute maximum ratings over operating free-air temperature range (unless otherwise noted)

Supply voltage, VCC (see Note 1)	7 1/
Input voltage: '122, '123, '130	/ V
7.5122 (1.5122)	5 V
'LS122, 'LS123	7 V
Operating free-air temperature range: SN54'	: 00
SN74'	, С
Storage temperature 0°C to 70)°C
Storage temperature range65°C to 150)°C

NOTE 1: Voltage values are with respect to network ground terminal.



recommended operating conditions

		SN54'			SN74'		
	MIN	NOM	MAX	MIN	NOM	MAX	UNIT
Supply voltage, V _{CC}	4.5	5	5.5	4.75	5	5.25	V
High-level output current, IOH			-800			800	μА
Low-level output current, IOL			16			16	mA
Pulse duration, t _W	40			40			ns
External timing resistance, R _{ext}	5		25	5		50	kΩ
External capacitance, C _{ext}		restrict			restrict		1,00
Wiring capacitance at Rext/Cext terminal			50	140	710311101	50	
Operating free-air temperature, TA	-55		125	0		70	pF °C

electrical characteristics over recommended free-air operating temperature range (unless otherwise noted)

	PARAMETER		TEST CO	NDITIONS†		122			123, 113	30	
			120100	- TONG	MIN	TYP#	MAX	MIN	TYP±	MAX	UNIT
VIH	High-level input voltage				2	· · · ·		2			V
VIL	Low-level input voltage						0.8			0.8	l v
VIK	Input clamp voltage		VCC = MIN,	I _I = -12 mA			-1.5			-1.5	V
Vон	High-level output voltage		V _{CC} = MIN, See Note 5	$I_{OH} = -800 \mu\text{A},$	2.4	3.4	1.5	2.4	3.4	-1.5	V
VoL	Low-level output voltage		V _{CC} = MIN, See Note 5	IOL = 16 mA,		0.2	0.4		0.2	0.4	V
11	Input current at maximum i	nput voltage	V _{CC} = MAX,	V _I = 5.5 V			1			1	mA
Ιн	High-level input current	Data inputs	V _{CC} = MAX,	V 2 4 V			40	_		40	1117
		Clear input	VCC - WAX,	V - 2,4 V			80			80	μΑ
HE	Low-level input current	Data inputs	V _{CC} = MAX,	V ₁ = 0.4.V			-1.6			-1.6	
		Clear input	VCC WAX,	V - 0.4 V			-3.2			-3.2	mA
los	Short-circuit output current	3	VCC = MAX,	See Note 5	-10		-40	-10		-40	mΑ
Icc	Supply current (quiescent o	r triggered)	V _{CC} = MAX,	See Notes 6 and 7		23	36		46	66	mA

[†] For conditions shown as MIN or MAX, use the appropriate value specified under recommended operating conditions.

NOTES: 5. Ground C_{ext} to measure V_{OH} at Q, V_{OL} at \overline{Q} , or I_{OS} at Q. C_{ext} is open to measure V_{OH} at \overline{Q} , V_{OL} at Q, or I_{OS} at \overline{Q} .

switching characteristics, VCC = 5 V, TA = 25°C, see note 8

DADAMETTO #	FROM	то			′	122, ′1	30		′123		
PARAMETER¶	(INPUT)	(OUTPUT)	TEST CON	TEST CONDITIONS		TYP	MAX	MIN	TYP	MAX	רואט
^t PLH	A	Q				22	33		22	33	
	В					19	28		19	28	ns
^t PHL	A	₫	$C_{ext} = 0$,	$R_{ext} = 5 k\Omega$,		30	40		30	40	
	В		C ₁ = 15 pF,	$R_1 = 400 \Omega$		27	36		27	36	ns
t _{PHL}	Clear	<u> </u>	· · · · · · · · · · · · · · · · · · ·	11 400 32		18	27		18	27	
tPLH						30	40		30	40	ns
t _{WQ} (min)	A or B	Q				45	65		45	76	ns
^t wQ	A or B	a	$C_{ext} = 1000 pF,$ $C_{L} = 15 pF,$	$R_{ext} = 10 \text{ k}\Omega$, $R_1 = 400 \Omega$	3.08	3.42	3.76	2.76	3,03	3.37	μs

TtpLH = propagation delay time, low-to-high-level output

NOTE 8: Load circuits and voltage waveforms are shown in Section 1.



 $^{^{\}ddagger}$ All typical values are at V_{CC} = 5 V, T_A = 25 °C.

[§] Not more than one output should be shorted at a time.

^{6.} Quiescent ICC is measured (after clearing) with 4.5 V applied to all clear and A inputs, B inputs grounded, all outputs open and R_{ext} = 25 k Ω . R_{int} of '122 is open.

^{7.} ICC is measured in the triggered state with 2.4 V applied to all clear and B inputs, A inputs grounded, all outputs open, $C_{ext} = 0.02 \,\mu\text{F}$, and $R_{ext} = 25 \,\text{k}\Omega$. R_{int} of '122 is open.

tpHL = propagation delay time, high-to-low-level output

 t_{WQ} = duration of pulse at output Q.

SN54LS122, SN54LS123, SN74LS122, SN74LS123 RETRIGGERABLE MONOSTABLE MULTIVIBRATORS

SDLS043 - DECEMBER 1983 - REVISED MARCH 1988

recommended operating conditions

		SN54LS	3'		SN74LS	3'	
	MIN	NOM	MAX	MIN	NOM	MAX	UNIT
Supply voltage, V _{CC}	4.5	5	5.5	4.75	5	5.25	V
High-level output current, IOH			-400			-400	μА
Low-level output current, IOL			4			8	mA
Pulse duration, t _W	40			40			ns
External timing resistance, R _{ext}	5		180	5		260	kΩ
External capacitance, C _{ext}	No	restrict	tion	No	restrict	ion	
Wiring capacitance at R _{ext} /C _{ext} terminal			50			50	pF
Operating free-air temperature, TA	-55		125	0		70	°C

electrical characteristics over recommended operating free-air temperature range (unless otherwise noted)

	PARAMETER	TEC	T CONDITIONS†			SN54LS	•		SN74LS	,	
	FARAMETER	1 53	T CONDITIONS,		MIN	TYP‡	MAX	MIN	TYP‡	MAX	UNIT
VIH	High-level input voltage				2			2			V
VIL	Low-level input voltage						0.7			0.8	V
VIK	Input clamp voltage	V _{CC} = MIN,	I _I = -18 mA				-1.5			-1.5	V
Vон	High-level output voltage	V _{CC} = MIN, V _{IL} = V _{IL} max	$V_{1H} = 2 V$, $I_{OH} = -400 \mu A$		2.5	3.5		2.7	3.5		V
VOL	Low-level output voltage	V _{CC} = MIN, V _{IL} = V _{IL} max	V _{IH} = 2 V,	I _{OL} = 4 mA		0.25	0.4		0.25 0.35	0.4	٧
l ₁	Input current at maximum input voltage	V _{CC} = MAX,	V _I = 7 V				0.1			0.1	mA
Iн	High-level input current	VCC = MAX,	V ₁ = 2.7 V				20			20	μΑ
IL	Low-level input current	V _{CC} = MAX,	V ₁ = 0.4 V				-0.4			-0.4	mA
los	Short-circuit output current§	V _{CC} = MAX			20		-100	-20		-100	mA
lcc	Supply current (quiescent or triggered)	V _{CC} = MAX,	See Note 13	'LS122 'LS123		6 12	11 20		6 12	11 20	mA

[†]For conditions shown as MIN or MAX, use the appropriate value specified under recommended operating conditions.

NOTES: 12. To measure VOH at Q, VOL at Q, or IOS at Q, ground Rext/Cext, apply 2 V to B and clear, and pulse A from 2 V to 0 V.

switching characteristics, VCC = 5 V, TA = 25°C (see note 8)

PARAMETER¶	FROM (INPUT)	TO (OUTPUT)	TEST CON	DITIONS	MIN	TYP	MAX	UNIT
tout	Α	α				23	33	
^t PLH	В	u u				23	44	ns
tPHL	Α	۵	C -0	D - 5 1:0		32	45	
PHL	В	α	C _{ext} = 0, C _L = 15 pF,	$R_{ext} = 5 k\Omega$, $R_L = 2 k\Omega$		34	56	ns
tPHL.	Clear	Q	CL = 15 pr,			20	27	
^t PLH	Cieal	ā				28	45	ns
t _{wQ} (min)	A or B	Q				116	200	ns
twQ	A or B	Q	C _{ext} = 1000 pF, C _L = 15 pF,	$R_{ext} = 10 k\Omega$, $R_L = 2 k\Omega$	4	4.5	5	μs

TtpLH = propagation delay time, low-to-high-level output



 $^{^{\}ddagger}$ All typical values are at V_{CC} = 5 V, T_A = 25 °C.

[§]Not more than one output should be shorted at a time and duration of the short-circuit should not exceed one second.

^{13.} With all outputs open and 4.5 V applied to all data and clear inputs. ICC is measured after a momentary ground, then 4.5 V, is applied to A or B inputs.

tpHL = propagation delay time, high-to-low-level output

 t_{WQ} = duration of pulse at output Q.

NOTE 8: Load circuits and voltage waveforms are shown in Section 1.

TYPICAL APPLICATION DATA FOR '122, '123, '130

For pulse durations when $C_{ext} \leq 1000$ pF, see Figure 4.

The output pulse duration is primarily a function of the external capacitor and resistor. For $C_{ext} > 1000 \ pF$, the output pulse duration (t_W) is defined as:

$$t_W = K \cdot R_T \cdot C_{ext} \left(1 + \frac{0.7}{R_T} \right)$$

where

K is 0.32 for '122, 0.28 for '123 and '130

 $R_{\mbox{\scriptsize T}}$ is in $k\Omega$ (internal or external timing resistance.)

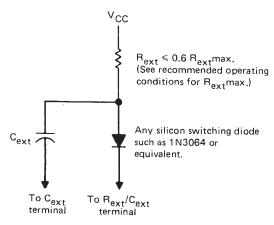
Cext is in pF

tw is in ns

To prevent reverse voltage across C_{ext} , it is recommended that the method shown in Figure 2 be employed when using electrolytic capacitors and in applications utilizing the clear function. In all applications using the diode, the pulse duration is:

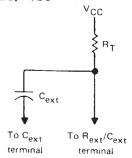
$$t_{W} = K_{D} \cdot R_{T} \cdot C_{ext} \left(1 + \frac{0.7}{R_{T}} \right)$$

Kp is 0.28 for '122, 0.25 for '123 and '130



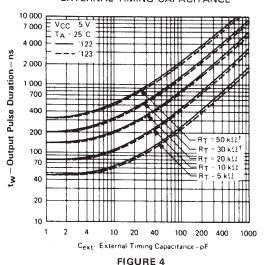
TIMING COMPONENT CONNECTIONS WHEN $C_{ext} \geq 1000 \; \text{pF AND CLEAR IS USED}$ FIGURE 2

Applications requiring more precise pulse durations (up to 28 seconds) and not requiring the clear feature can best be satisfied with the '121.



TIMING COMPONENT CONNECTIONS FIGURE 3

TYPICAL OUTPUT PULSE DURATION vs
EXTERNAL TIMING CAPACITANCE



[†]These values of resistance exceed the maximum recommended for use over the full temperature range of the SN54' circuits.

SDLS043 - DECEMBER 1983 - REVISED MARCH 1988

TYPICAL APPLICATION DATA FOR 'LS122, 'LS123

The basic output pulse duration is essentially determined by the values of external capacitance and timing resistance. For pulse durations when Cext≤1000 pF, use Figure 6, or use Figure 7 where the pulse duration may be defined as:

$$t_W = K \cdot R_T \cdot C_{ext}$$

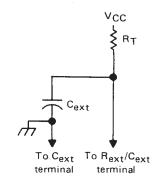
When $C_{ext} \ge 1 \mu F$, the output pulse width is defined

$$t_W = 0.33 \cdot R_T \cdot C_{ext}$$

For the above two equations, as applicable;

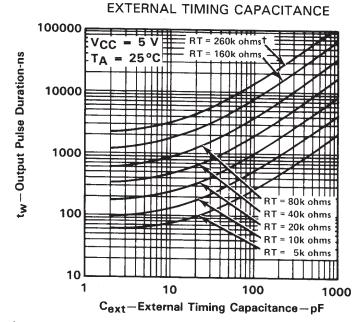
K is multiplier factor, see Figure 7 $R_{\mbox{\scriptsize T}}$ is in $k\Omega$ (internal or external timing resistance) Cext is in pF tw is in ns

For maximum noise immunity, system ground should be applied to the Cext node, even though the Cext node is already tied to the ground lead internally. Due to the timing scheme used by the 'LS122 and 'LS123. a switching diode is not required to prevent reverse biasing when using electolytic capacitors.



TIMING COMPONENT CONNECTIONS FIGURE 5

'LS122, 'LS123 TYPICAL OUTPUT PULSE DURATION



[†]This value of resistance exceeds the maximum recommended for use over the full temperature range of the SN54LS circuits.

FIGURE 6



TYPICAL APPLICATION DATA FOR 'LS122, 'LS123†



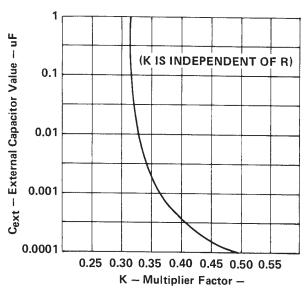
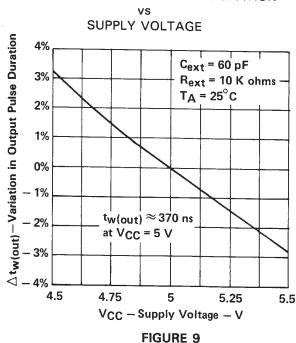


FIGURE 7

VARIATION IN OUTPUT PULSE DURATION



DISTRIBUTION OF UNITS vs OUTPUT PULSE DURATION

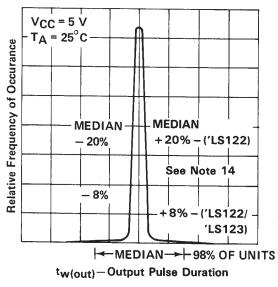


FIGURE 8

VARIATION IN OUTPUT PULSE DURATION

vs FREE-AIR TEMPERATURE

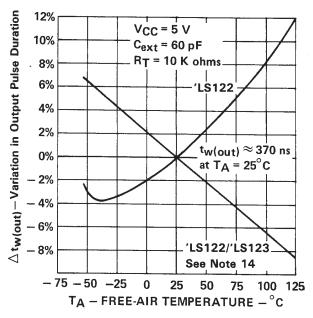


FIGURE 10

NOTE 14: For the 'LS122, the internal timing resistor, R_{int} was used. For the 'LS122/123, an external timing resistor was used for R_T.

†Data for temperatures below 0°C and above 70°C and for suply voltages below 4.75 V and above 5.25 V are applicable for SN54LS122 and SN54LS123 only.





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PACKAGING INFORMATION

Orderable Device	Status	Package Type	Package Drawing	Pins	Package Qty	Eco Plan	Lead finish/ Ball material	MSL Peak Temp	Op Temp (°C)	Device Marking (4/5)	Samples
5962-7603901VEA	ACTIVE	CDIP	J	16	1	Non-RoHS & Green	SNPB	N / A for Pkg Type	-55 to 125	5962-7603901VE A SNV54LS123J	Samples
5962-7603901VFA	ACTIVE	CFP	W	16	1	Non-RoHS & Green	SNPB	N / A for Pkg Type	-55 to 125	5962-7603901VF A SNV54LS123W	Samples
7603901EA	ACTIVE	CDIP	J	16	1	Non-RoHS & Green	SNPB	N / A for Pkg Type	-55 to 125	7603901EA SNJ54LS123J	Samples
7603901FA	ACTIVE	CFP	W	16	1	Non-RoHS & Green	SNPB	N / A for Pkg Type	-55 to 125	7603901FA SNJ54LS123W	Samples
JM38510/01203BEA	ACTIVE	CDIP	J	16	1	Non-RoHS & Green	SNPB	N / A for Pkg Type	-55 to 125	JM38510/ 01203BEA	Samples
JM38510/31401B2A	ACTIVE	LCCC	FK	20	1	Non-RoHS & Green	SNPB	N / A for Pkg Type	-55 to 125	JM38510/ 31401B2A	Samples
JM38510/31401BEA	ACTIVE	CDIP	J	16	1	Non-RoHS & Green	SNPB	N / A for Pkg Type	-55 to 125	JM38510/ 31401BEA	Samples
JM38510/31401BFA	ACTIVE	CFP	W	16	1	Non-RoHS & Green	SNPB	N / A for Pkg Type	-55 to 125	JM38510/ 31401BFA	Samples
M38510/01203BEA	ACTIVE	CDIP	J	16	1	Non-RoHS & Green	SNPB	N / A for Pkg Type	-55 to 125	JM38510/ 01203BEA	Samples
M38510/31401B2A	ACTIVE	LCCC	FK	20	1	Non-RoHS & Green	SNPB	N / A for Pkg Type	-55 to 125	JM38510/ 31401B2A	Samples
M38510/31401BEA	ACTIVE	CDIP	J	16	1	Non-RoHS & Green	SNPB	N / A for Pkg Type	-55 to 125	JM38510/ 31401BEA	Samples
M38510/31401BFA	ACTIVE	CFP	W	16	1	Non-RoHS & Green	SNPB	N / A for Pkg Type	-55 to 125	JM38510/ 31401BFA	Samples
SN54123J	ACTIVE	CDIP	J	16	1	Non-RoHS & Green	SNPB	N / A for Pkg Type	-55 to 125	SN54123J	Samples
SN54LS123J	ACTIVE	CDIP	J	16	1	Non-RoHS & Green	SNPB	N / A for Pkg Type	-55 to 125	SN54LS123J	Samples
SN74123N	ACTIVE	PDIP	N	16	25	RoHS & Green	NIPDAU	N / A for Pkg Type	0 to 70	SN74123N	Samples
SN74LS122D	ACTIVE	SOIC	D	14	50	RoHS & Green	NIPDAU	Level-1-260C-UNLIM	0 to 70	LS122	Samples



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Orderable Device	Status (1)	Package Type	Package Drawing	Pins	Package Qty	Eco Plan	Lead finish/ Ball material	MSL Peak Temp	Op Temp (°C)	Device Marking (4/5)	Samples
SN74LS122DR	ACTIVE	SOIC	D	14	2500	RoHS & Green	NIPDAU	Level-1-260C-UNLIM	0 to 70	LS122	Samples
SN74LS122DRE4	ACTIVE	SOIC	D	14	2500	RoHS & Green	NIPDAU	Level-1-260C-UNLIM	0 to 70	LS122	Samples
SN74LS122N	ACTIVE	PDIP	N	14	25	RoHS & Green	NIPDAU	N / A for Pkg Type	0 to 70	SN74LS122N	Samples
SN74LS122NSR	ACTIVE	SO	NS	14	2000	RoHS & Green	NIPDAU	Level-1-260C-UNLIM	0 to 70	74LS122	Samples
SN74LS123D	ACTIVE	SOIC	D	16	40	RoHS & Green	NIPDAU	Level-1-260C-UNLIM	0 to 70	LS123	Samples
SN74LS123DBR	ACTIVE	SSOP	DB	16	2000	RoHS & Green	NIPDAU	Level-1-260C-UNLIM		LS123	Samples
SN74LS123DE4	ACTIVE	SOIC	D	16	40	RoHS & Green	NIPDAU	Level-1-260C-UNLIM	0 to 70	LS123	Samples
SN74LS123DR	ACTIVE	SOIC	D	16	2500	RoHS & Green	NIPDAU	Level-1-260C-UNLIM	0 to 70	LS123	Samples
SN74LS123DRG4	ACTIVE	SOIC	D	16	2500	RoHS & Green	NIPDAU	Level-1-260C-UNLIM	0 to 70	LS123	Samples
SN74LS123N	ACTIVE	PDIP	N	16	25	RoHS & Green	NIPDAU	N / A for Pkg Type	0 to 70	SN74LS123N	Samples
SN74LS123NE4	ACTIVE	PDIP	N	16	25	RoHS & Green	NIPDAU	N / A for Pkg Type	0 to 70	SN74LS123N	Samples
SN74LS123NSR	ACTIVE	SO	NS	16	2000	RoHS & Green	NIPDAU	Level-1-260C-UNLIM	0 to 70	74LS123	Samples
SN74LS123NSRG4	ACTIVE	SO	NS	16	2000	RoHS & Green	NIPDAU	Level-1-260C-UNLIM	0 to 70	74LS123	Samples
SNJ54123J	ACTIVE	CDIP	J	16	1	Non-RoHS & Green	SNPB	N / A for Pkg Type	-55 to 125	SNJ54123J	Samples
SNJ54123W	ACTIVE	CFP	W	16	1	Non-RoHS & Green	SNPB	N / A for Pkg Type	-55 to 125	SNJ54123W	Samples
SNJ54LS123FK	ACTIVE	LCCC	FK	20	1	Non-RoHS & Green	SNPB	N / A for Pkg Type	-55 to 125	SNJ54LS 123FK	Samples
SNJ54LS123J	ACTIVE	CDIP	J	16	1	Non-RoHS & Green	SNPB	N / A for Pkg Type	-55 to 125	7603901EA SNJ54LS123J	Samples
SNJ54LS123W	ACTIVE	CFP	W	16	1	Non-RoHS & Green	SNPB	N / A for Pkg Type	-55 to 125	7603901FA SNJ54LS123W	Samples

(1) The marketing status values are defined as follows:

ACTIVE: Product device recommended for new designs.

LIFEBUY: TI has announced that the device will be discontinued, and a lifetime-buy period is in effect.

PACKAGE OPTION ADDENDUM

www.ti.com 1-Jun-2023

NRND: Not recommended for new designs. Device is in production to support existing customers, but TI does not recommend using this part in a new design.

PREVIEW: Device has been announced but is not in production. Samples may or may not be available.

OBSOLETE: TI has discontinued the production of the device.

(2) RoHS: TI defines "RoHS" to mean semiconductor products that are compliant with the current EU RoHS requirements for all 10 RoHS substances, including the requirement that RoHS substance do not exceed 0.1% by weight in homogeneous materials. Where designed to be soldered at high temperatures, "RoHS" products are suitable for use in specified lead-free processes. TI may reference these types of products as "Pb-Free".

RoHS Exempt: TI defines "RoHS Exempt" to mean products that contain lead but are compliant with EU RoHS pursuant to a specific EU RoHS exemption.

Green: TI defines "Green" to mean the content of Chlorine (CI) and Bromine (Br) based flame retardants meet JS709B low halogen requirements of <=1000ppm threshold. Antimony trioxide based flame retardants must also meet the <=1000ppm threshold requirement.

- (3) MSL, Peak Temp. The Moisture Sensitivity Level rating according to the JEDEC industry standard classifications, and peak solder temperature.
- (4) There may be additional marking, which relates to the logo, the lot trace code information, or the environmental category on the device.
- (5) Multiple Device Markings will be inside parentheses. Only one Device Marking contained in parentheses and separated by a "~" will appear on a device. If a line is indented then it is a continuation of the previous line and the two combined represent the entire Device Marking for that device.
- (6) Lead finish/Ball material Orderable Devices may have multiple material finish options. Finish options are separated by a vertical ruled line. Lead finish/Ball material values may wrap to two lines if the finish value exceeds the maximum column width.

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OTHER QUALIFIED VERSIONS OF SN54123, SN54LS123, SN54LS123-SP, SN74123, SN74LS123:

Catalog: SN74123, SN74LS123, SN54LS123

Military: SN54123, SN54LS123

Space: SN54LS123-SP

NOTE: Qualified Version Definitions:



PACKAGE OPTION ADDENDUM

www.ti.com 1-Jun-2023

- Catalog TI's standard catalog product
- Military QML certified for Military and Defense Applications
- Space Radiation tolerant, ceramic packaging and qualified for use in Space-based application

PACKAGE MATERIALS INFORMATION

www.ti.com 1-Jul-2023

TAPE AND REEL INFORMATION





A0	Dimension designed to accommodate the component width
В0	Dimension designed to accommodate the component length
K0	Dimension designed to accommodate the component thickness
W	Overall width of the carrier tape
P1	Pitch between successive cavity centers

QUADRANT ASSIGNMENTS FOR PIN 1 ORIENTATION IN TAPE



*All dimensions are nominal

Device	Package Type	Package Drawing		SPQ	Reel Diameter (mm)	Reel Width W1 (mm)	A0 (mm)	B0 (mm)	K0 (mm)	P1 (mm)	W (mm)	Pin1 Quadrant
SN74LS122DR	SOIC	D	14	2500	330.0	16.4	6.5	9.0	2.1	8.0	16.0	Q1
SN74LS122NSR	so	NS	14	2000	330.0	16.4	8.2	10.5	2.5	12.0	16.0	Q1
SN74LS123DBR	SSOP	DB	16	2000	330.0	16.4	8.35	6.6	2.4	12.0	16.0	Q1
SN74LS123DR	SOIC	D	16	2500	330.0	16.4	6.5	10.3	2.1	8.0	16.0	Q1
SN74LS123NSR	so	NS	16	2000	330.0	16.4	8.2	10.5	2.5	12.0	16.0	Q1



www.ti.com 1-Jul-2023



*All dimensions are nominal

7 III GIII IOI IOI IOI IOI III IOI							
Device	Package Type	Package Drawing	Pins	SPQ	Length (mm)	Width (mm)	Height (mm)
SN74LS122DR	SOIC	D	14	2500	356.0	356.0	35.0
SN74LS122NSR	so	NS	14	2000	356.0	356.0	35.0
SN74LS123DBR	SSOP	DB	16	2000	356.0	356.0	35.0
SN74LS123DR	SOIC	D	16	2500	340.5	336.1	32.0
SN74LS123NSR	so	NS	16	2000	356.0	356.0	35.0



www.ti.com 1-Jul-2023

TUBE



*All dimensions are nominal

Device	Package Name	Package Type	Pins	SPQ	L (mm)	W (mm)	T (µm)	B (mm)
5962-7603901VFA	W	CFP	16	1	506.98	26.16	6220	NA
JM38510/31401B2A	FK	LCCC	20	1	506.98	12.06	2030	NA
JM38510/31401BFA	W	CFP	16	1	506.98	26.16	6220	NA
M38510/31401B2A	FK	LCCC	20	1	506.98	12.06	2030	NA
M38510/31401BFA	W	CFP	16	1	506.98	26.16	6220	NA
SN74123N	N	PDIP	16	25	506	13.97	11230	4.32
SN74123N	N	PDIP	16	25	506	13.97	11230	4.32
SN74LS122D	D	SOIC	14	50	506.6	8	3940	4.32
SN74LS122N	N	PDIP	14	25	506	13.97	11230	4.32
SN74LS122N	N	PDIP	14	25	506	13.97	11230	4.32
SN74LS123D	D	SOIC	16	40	507	8	3940	4.32
SN74LS123DE4	D	SOIC	16	40	507	8	3940	4.32
SN74LS123N	N	PDIP	16	25	506	13.97	11230	4.32
SN74LS123N	N	PDIP	16	25	506	13.97	11230	4.32
SN74LS123NE4	N	PDIP	16	25	506	13.97	11230	4.32
SN74LS123NE4	N	PDIP	16	25	506	13.97	11230	4.32
SNJ54123W	W	CFP	16	1	506.98	26.16	6220	NA
SNJ54LS123FK	FK	LCCC	20	1	506.98	12.06	2030	NA

D (R-PDS0-G16)

PLASTIC SMALL OUTLINE



- A. All linear dimensions are in inches (millimeters).
- B. This drawing is subject to change without notice.
- Body length does not include mold flash, protrusions, or gate burrs. Mold flash, protrusions, or gate burrs shall not exceed 0.006 (0,15) each side.
- Body width does not include interlead flash. Interlead flash shall not exceed 0.017 (0,43) each side.
- E. Reference JEDEC MS-012 variation AC.



D (R-PDSO-G16)

PLASTIC SMALL OUTLINE



- A. All linear dimensions are in millimeters.
- B. This drawing is subject to change without notice.
- C. Publication IPC-7351 is recommended for alternate designs.
- D. Laser cutting apertures with trapezoidal walls and also rounding corners will offer better paste release. Customers should contact their board assembly site for stencil design recommendations. Refer to IPC-7525 for other stencil recommendations.
- E. Customers should contact their board fabrication site for solder mask tolerances between and around signal pads.





SMALL OUTLINE PACKAGE



- 1. All linear dimensions are in millimeters. Any dimensions in parenthesis are for reference only. Dimensioning and tolerancing per ASME Y14.5M.

 2. This drawing is subject to change without notice.

 3. This dimension does not include mold flash, protrusions, or gate burrs. Mold flash, protrusions, or gate burrs shall not
- exceed 0.15 mm per side.
 4. Reference JEDEC registration MO-150.



SMALL OUTLINE PACKAGE



NOTES: (continued)

- 5. Publication IPC-7351 may have alternate designs.
- 6. Solder mask tolerances between and around signal pads can vary based on board fabrication site.



SMALL OUTLINE PACKAGE



NOTES: (continued)

- 7. Laser cutting apertures with trapezoidal walls and rounded corners may offer better paste release. IPC-7525 may have alternate design recommendations.
- 8. Board assembly site may have different recommendations for stencil design.



MECHANICAL DATA

NS (R-PDSO-G**)

14-PINS SHOWN

PLASTIC SMALL-OUTLINE PACKAGE



- A. All linear dimensions are in millimeters.
- B. This drawing is subject to change without notice.
- C. Body dimensions do not include mold flash or protrusion, not to exceed 0,15.



W (R-GDFP-F16)

CERAMIC DUAL FLATPACK



- A. All linear dimensions are in inches (millimeters).
- B. This drawing is subject to change without notice.
- C. This package can be hermetically sealed with a ceramic lid using glass frit.
- D. Index point is provided on cap for terminal identification only.
- E. Falls within MIL STD 1835 GDFP2-F16



8.89 x 8.89, 1.27 mm pitch

LEADLESS CERAMIC CHIP CARRIER

This image is a representation of the package family, actual package may vary. Refer to the product data sheet for package details.



14 LEADS SHOWN



- A. All linear dimensions are in inches (millimeters).
- B. This drawing is subject to change without notice.
- C. This package is hermetically sealed with a ceramic lid using glass frit.
- D. Index point is provided on cap for terminal identification only on press ceramic glass frit seal only.
- E. Falls within MIL STD 1835 GDIP1-T14, GDIP1-T16, GDIP1-T18 and GDIP1-T20.

D (R-PDSO-G14)

PLASTIC SMALL OUTLINE



- A. All linear dimensions are in inches (millimeters).
- B. This drawing is subject to change without notice.
- Body length does not include mold flash, protrusions, or gate burrs. Mold flash, protrusions, or gate burrs shall not exceed 0.006 (0,15) each side.
- Body width does not include interlead flash. Interlead flash shall not exceed 0.017 (0,43) each side.
- E. Reference JEDEC MS-012 variation AB.



D (R-PDSO-G14)

PLASTIC SMALL OUTLINE



- A. All linear dimensions are in millimeters.
- B. This drawing is subject to change without notice.
- C. Publication IPC-7351 is recommended for alternate designs.
- D. Laser cutting apertures with trapezoidal walls and also rounding corners will offer better paste release. Customers should contact their board assembly site for stencil design recommendations. Refer to IPC-7525 for other stencil recommendations.
- E. Customers should contact their board fabrication site for solder mask tolerances between and around signal pads.



N (R-PDIP-T**)

PLASTIC DUAL-IN-LINE PACKAGE

16 PINS SHOWN



- A. All linear dimensions are in inches (millimeters).
- B. This drawing is subject to change without notice.
- Falls within JEDEC MS-001, except 18 and 20 pin minimum body length (Dim A).
- The 20 pin end lead shoulder width is a vendor option, either half or full width.





SOP



- 1. All linear dimensions are in millimeters. Dimensions in parenthesis are for reference only. Dimensioning and tolerancing
- per ASME Y14.5M.

 2. This drawing is subject to change without notice.

 3. This dimension does not include mold flash, protrusions, or gate burrs. Mold flash, protrusions, or gate burrs shall not exceed 0.15 mm, per side.
- 4. This dimension does not include interlead flash. Interlead flash shall not exceed 0.25 mm, per side.



SOF



NOTES: (continued)

- 5. Publication IPC-7351 may have alternate designs.
- 6. Solder mask tolerances between and around signal pads can vary based on board fabrication site.



SOF



NOTES: (continued)

- 7. Laser cutting apertures with trapezoidal walls and rounded corners may offer better paste release. IPC-7525 may have alternate design recommendations.
- 8. Board assembly site may have different recommendations for stencil design.



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